

PLASMA PREP Jr. APPLICATIONS

Plasma Prep Jr Applications

<u>APPLICATION</u>	<u>USE</u>
Wire Bond Pad Cleaning	The presence of contamination on the die pad causes the wire under the ultrasonic tool to slip and not generate the heat required to weld the wire to the die pad.
Cleaning Pd-Ag Die Attach Pads	Sputters away the oxygen of the silver oxide and removes surface organics
Cleaning Gold Plated Parts	Sputters away the oxygen of the gold oxide
Epoxy Bleed Removal	Epoxy bleed is caused during die attachment with epoxy adhesive. The epoxy components have different affinity for the ceramic substrate. Some of the components wet the substrate beyond the footprint of the die. This is referred to as epoxy bleed. Sputters or oxidizes the epoxy bleed
Photoresist Removal	Photoresist removal and via descumming can be oxidized using an oxygen plasma.
Cleaning Ceramic Substrates	Sputters or oxidizes the organic contaminants
Cleaning Glass Parts	Sputters or oxidizes the organic contaminants
Cleaning Optics	Sputters or oxidizes the organic contaminants
Cleaning Semiconductor Surfaces	Sputters or oxidizes the organic contaminants
Removal of Plastic Encapsulants for Failure Mode Analysis	Oxidizes the encapsulant, in conjunction with CF4 or SF6 removes SiO2 filler
Surface Preparation of Plastics for Gluing	Surface oxidation forming -OH and epoxy bonds.
Cleaning Silver Plated Parts	Sputters away the oxygen of the silver oxide and removes surface organics
Reduction of Some Metal Oxides	Sputters away the oxygen
Removal of Oil or Epoxy Residues	Sputters or oxidizes the oil or epoxy